AMENDMENTS TO THE CLAIMS

The listing of claims below replaces all prior versions of claims in the application.

1. (Currently Amended): A cooling device ~~for an electronic component~~, comprising:

a first electrode to contact with an electronic component to be cooled;

a second electrode;

a thermoelectric conversion material disposed between ~~two electrodes that function as a cathode and an anode and are~~ the first electrode and the second electrode;

electric conductor directly connecting the first electrode and the second electrode making the first electrode and the second electrode electrically short-circuited~~, the cooling device being brought into contact with an electronic component requiring cooling so that one electrode side in contact with the thermoelectric conversion material becomes a low-temperature side and the other electrode side becomes a high-temperature side, a temperature difference between the two electrodes causing the thermoelectric conversion material to produce a thermoelectromotive force which generates current to cool the high-temperature side~~.

2. (Currently Amended): The cooling device for an electronic component according to Claim 1, wherein the thermoelectric conversion material is ~~either~~ one selected from the group of a p-type material [[or]], an n-type material [[or]], and a combination of p-type and n-type materials arranged alternately in series.

3. (Currently Amended): ~~A cooling system comprising~~ The cooling device according to Claim 1, wherein two or more cooling devices are stacked ~~cooling devices according to Claim 1~~.

4. (Currently Amended): ~~A cooling system comprising the~~ The cooling device according to Claim 1, wherein the cooling device is used in a cooling system.

5. (New): The cooling device for an electronic component according to Claim 2, wherein the thermoelectric conversion material is a p-type material.

6. (New): The cooling device for an electronic component according to Claim 2, wherein the thermoelectric conversion material is an n-type material.

7. (New): The cooling device for an electronic component according to Claim 2, wherein the thermoelectric conversion material is a combination of p-type and n-type materials arranged alternately in series.